

描述 / Descriptions

TO-277

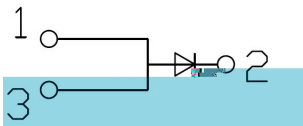
TO-277 Plastic package Schottky diode .

特征 / Features

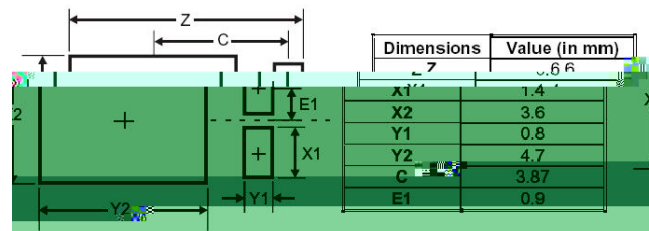
High Forward Surge Capability, Low Forward Voltage Drop $V_F(\text{typ})=0.32\text{V}$, Excellent High Temperature Stability. HF Product.

用途 / Applications

For use in low voltage, high frequency inverters, free wheeling, and polarity protection applications.

内部等效电路 / Equivalent Circuit**引脚排列 / Pinning**

PIN1 Anode PIN 2 Cathode PIN 3 Anode



Suggested Pad layout

放大及印章代码 / h_{FE} Classifications & Marking

See Marking Instructions.

极限参数 / Absolute Maximum Ratings(Ta=25°C)

Parameter	Symbol	Rating	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage Peak Reverse Voltage	V_{RRM} V_{RWM} V_{RM}	60	V
RMS Reverse voltage	$V_{R(RMS)}$	42	V
Average Rectified Output Current	I_O	10	A
Non-Repetitive Peak Forward Surge Current	I_{FSM}	150	A
Junction Temperature Range	$T_{J\ MAX}$	150	
Storage Temperature Range	T_{stg}	-55 150	
Typical Thermal Resistance	$R_{\theta JA}$ Note 1	76	/W

电性能参数 / Electrical Characteristics(Ta=25°C)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Reverse Voltage	V_{BR}	$I_R=0.5mA$	60			V
Forward voltage	V_F	$I_F=2A$ $T_J=25$		0.42	0.47	V
		$I_F=2A$ $T_J=125$		0.32		V
		$I_F=10A$ $T_J=25$		0.6	0.65	V
		$I_F=10A$ $T_J=125$		0.54		V
Instantaneous Reverse Current	I_R Note 1	$V_R=60V$ $T_J=25$		50	100	μA
		$V_R=60V$ $T_J=100$			10	mA
		$V_R=60V$ $T_J=125$			50	mA

Notes

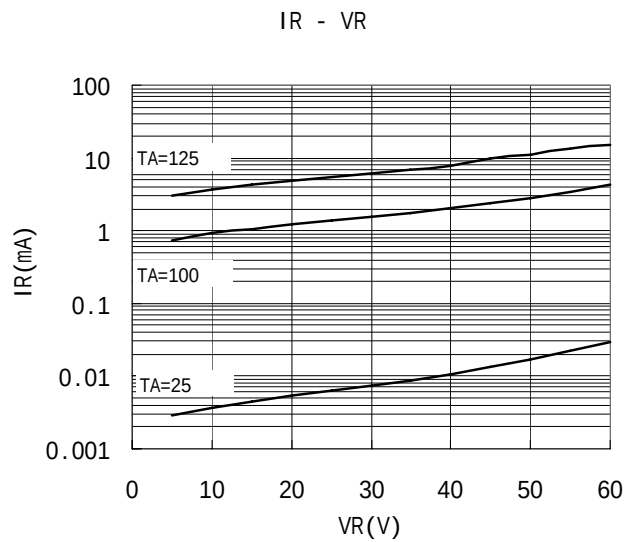
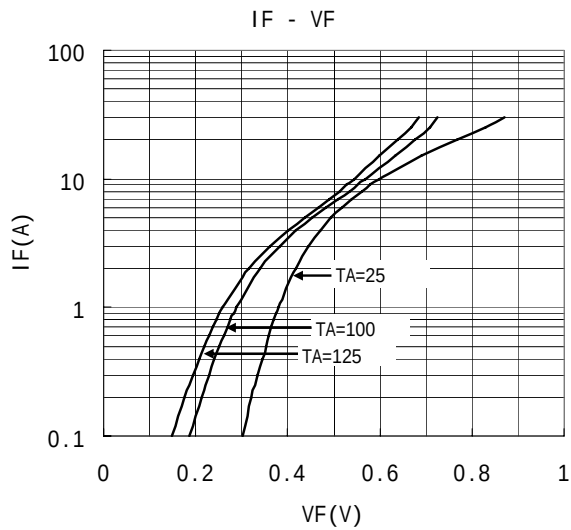
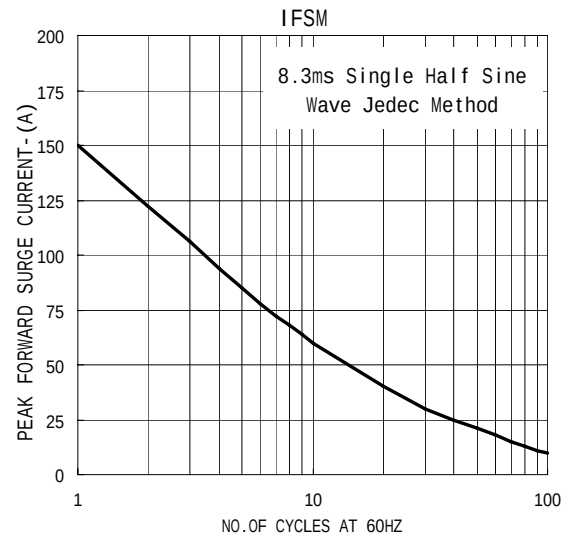
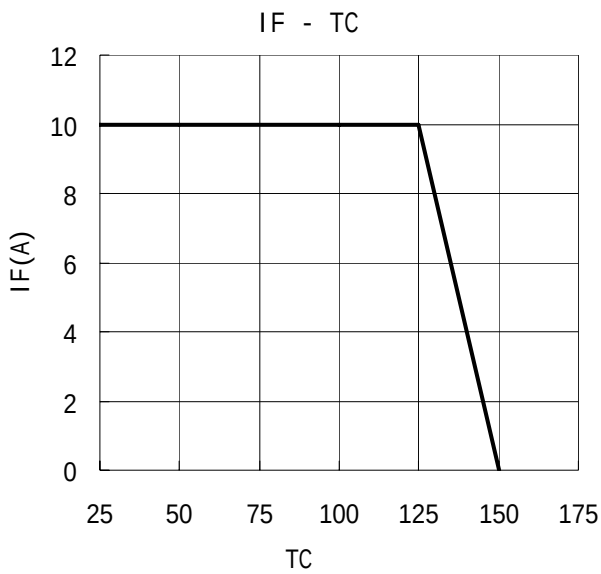
/FR-4 PCB, 2oz. Copper, minimum recommended pad

layout per.

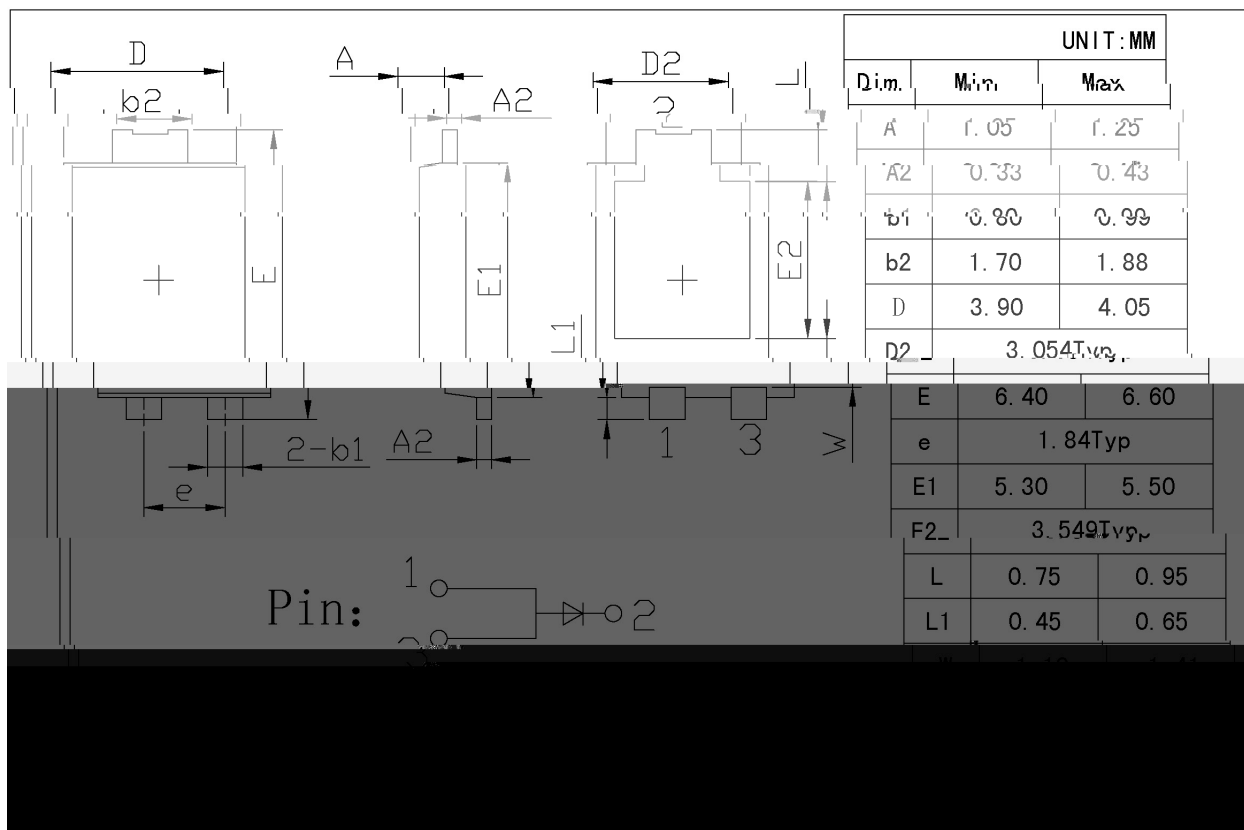
Short duration pulse test used to minimize self-heating

effect.

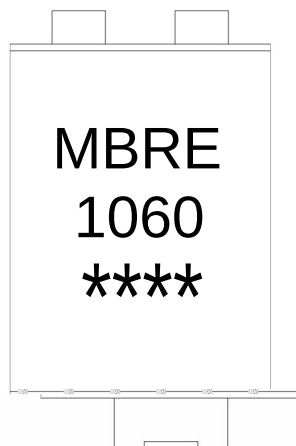
电参数曲线图 / Electrical Characteristic Curve



外形尺寸图 / Package Dimensions



印章说明 / Marking Instructions



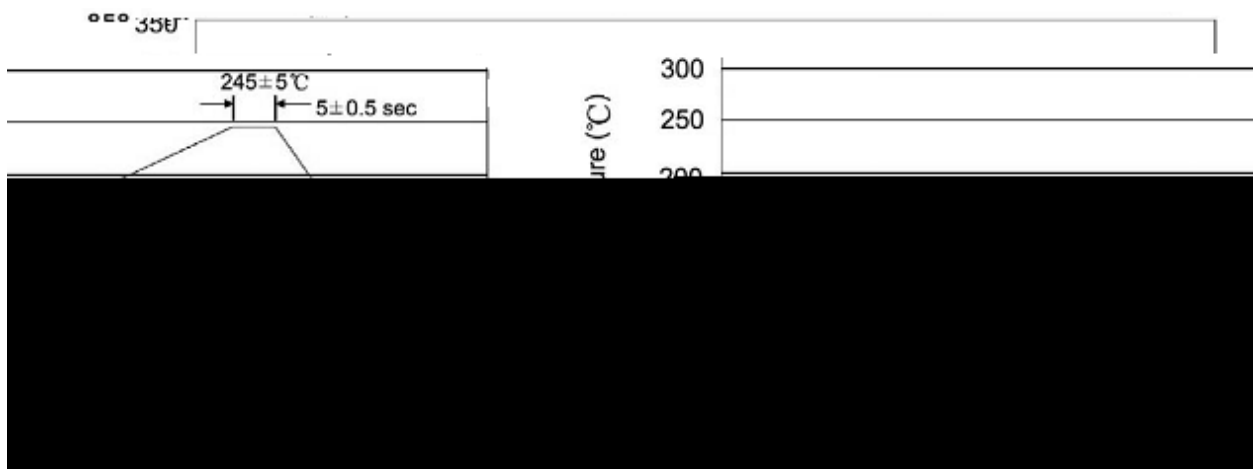
Note:

Product Type.

****:

Lot No. Code, code change with Lot No.

回流焊温度曲线图(无铅) / Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

- | | | | | | |
|---|-----|-----|----|---------|---|
| 1 | 150 | 180 | 60 | 90sec; | 1.Preheating:150~180 , Time:60~90sec. |
| 2 | 245 | 5 | 5 | 0.5sec; | 2.Peak Temp.:245 5 , Duration:5 0.5sec. |
| 3 | | 2 | 10 | /sec. | 3. Cooling Speed: 2~10 /sec. |

耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions

260 ±5 10 ±1 sec. Temp.:260±5 Time:10±1 sec

包装规格 / Packaging SPEC.

/ REEL

Package Type	Units					Dimension (unit mm ³)		
	Units/Reel /	Reels/Inner Box /	Units/Inner Box /	Inner Boxes/Outer Box /	Units/Outer Box /	Reel	Inner Box	Outer Box
TO-277	5,000	3	15,000	6	90,000	13 ×12	360×360×50	380×335×366

使用说明 / Notices